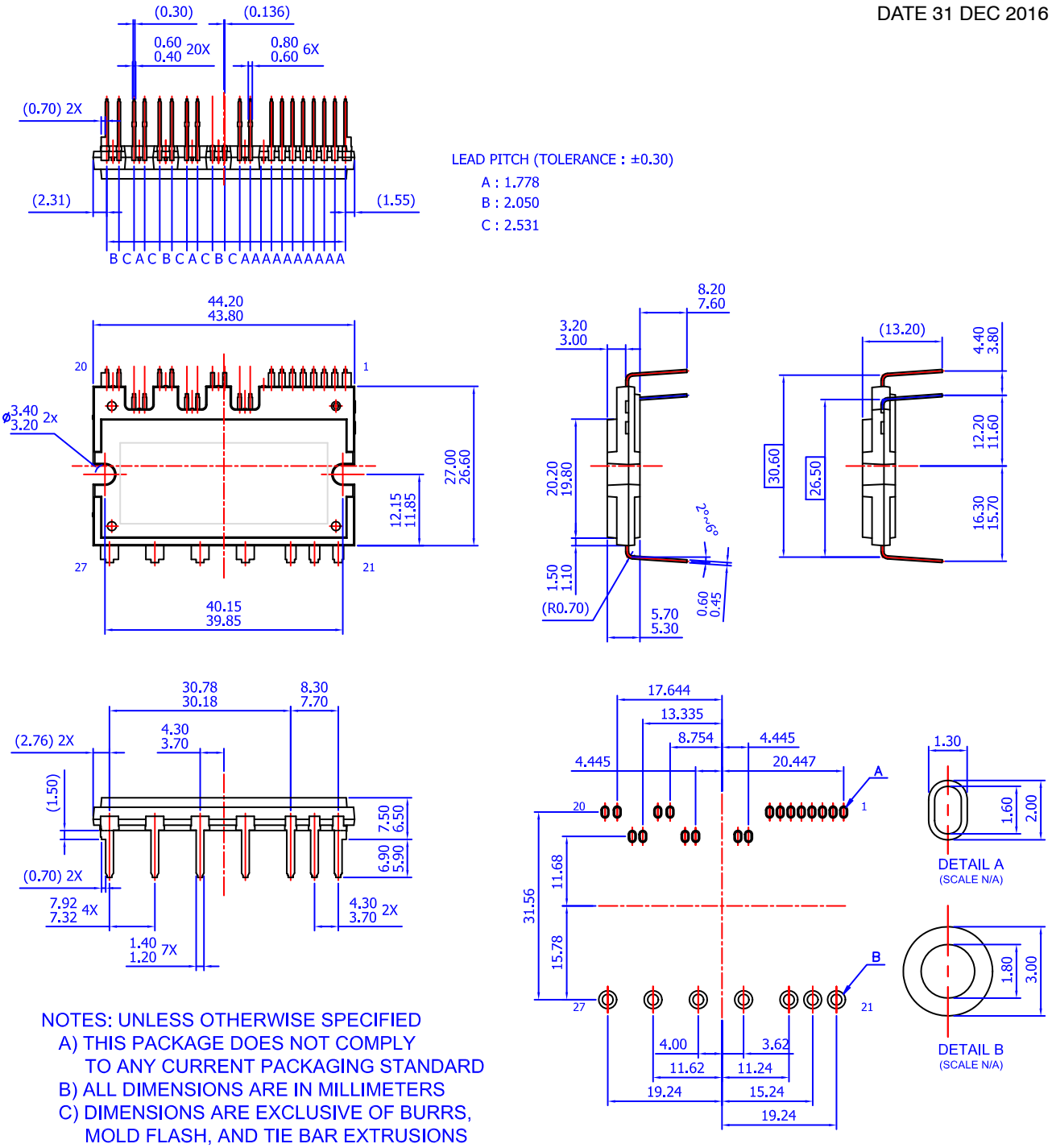
SPMIA−027 / 27LD, PDD, BOOST PFCM SPM27−IA
CASE MODDJ
ISSUE O

DATE 31 DEC 2016



NOTES: UNLESS OTHERWISE SPECIFIED
A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
B) ALL DIMENSIONS ARE IN MILLIMETERS
C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
D) ( ) IS REFERENCE
E) [ ] IS ASS'Y QUALITY

LAND PATTERN RECOMMENDATIONS

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